

**描述 / Descriptions**

肖特基整流二极管，薄型 SOD-323FL 封装。

Schottky Barrier Rectifiers,SOD-323FL thin package.

**特征 / Features**

低功耗，高效率，高电流，正向压降低，浪涌能力高，适用于低压，高频逆变器。无卤产品。

Low power loss, high efficiency . High current capability , low forward voltage drop , High surge capability, For use in low voltage, high frequency inverters .Halogen free product.

**用途 / Applications**

一般用途。 .

General purpose.

**内部等效电路 / Equivalent Circuit**

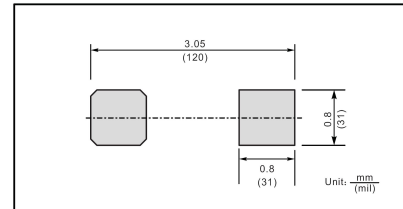


**引脚排列 / Pinning**



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



**印章代码 / Marking**

见印章说明。 See Marking Instructions.

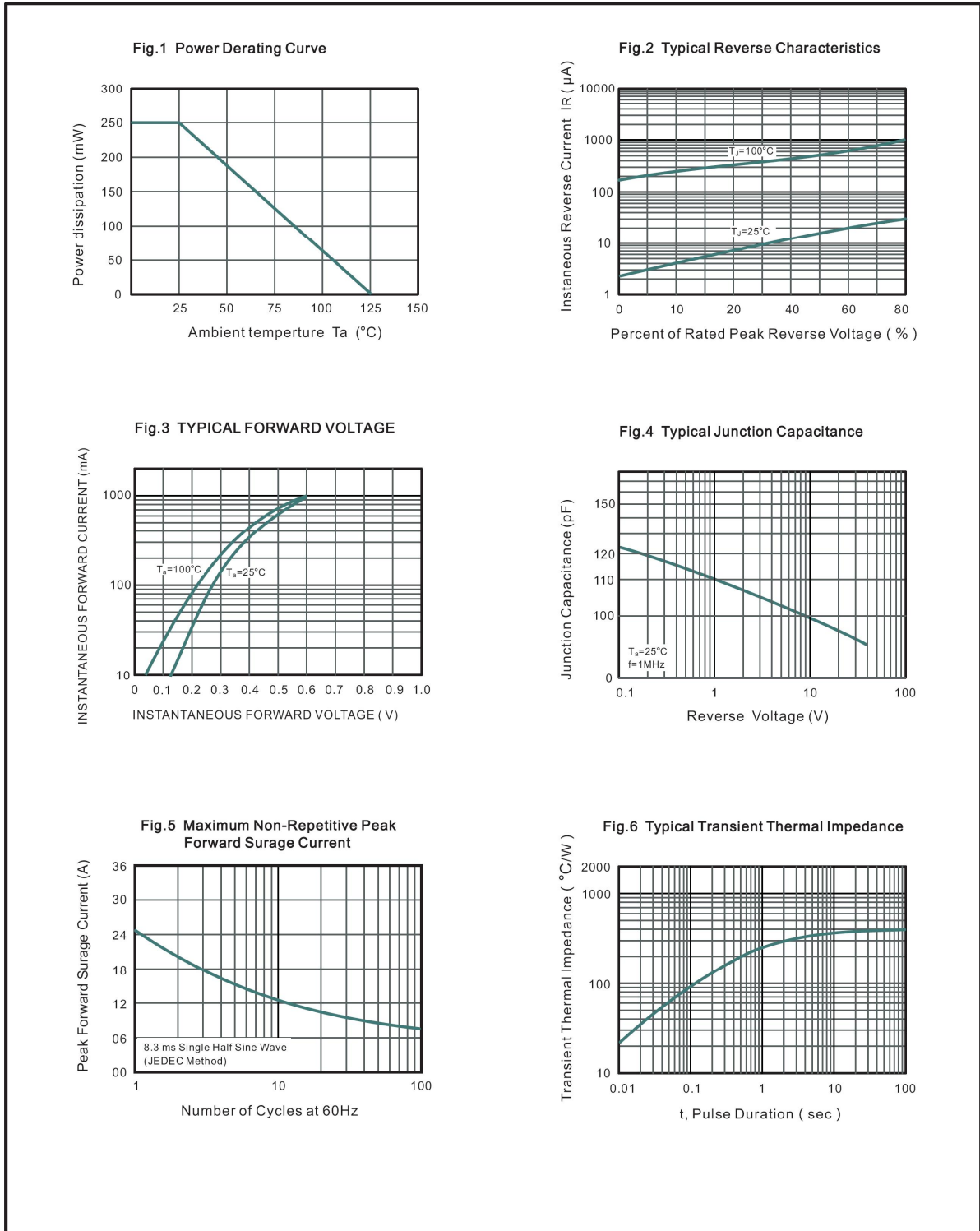
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
		B16WSFL	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V
Maximum RMS voltage	$V_{RMS}$	42	V
Maximum DC Blocking Voltage	$V_{DC}$	60	V
Continuous forward current	$I_F (AV)$	1.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	$I_{FSM}$	25	A
Total capacitance VR=4V,f=1MHz	$C_{tot}$	120	pF
Total power dissipation	$P_{tot}$	250	mW
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	400	°C/W
Junction Temperature	$T_j$	125	°C
Storage Temperature	$T_{stg}$	-55 ~ +150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
			B16WSFL	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=1.0A$	0.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$V_R=60V$	0.1	mA

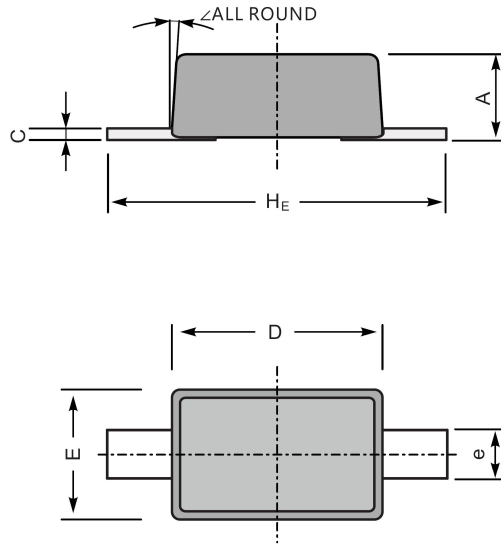
电参数曲线图 / Electrical Characteristic Curve



**外形尺寸图 / Package Dimensions**

Plastic surface mounted package; 2 leads

SOD-323FL

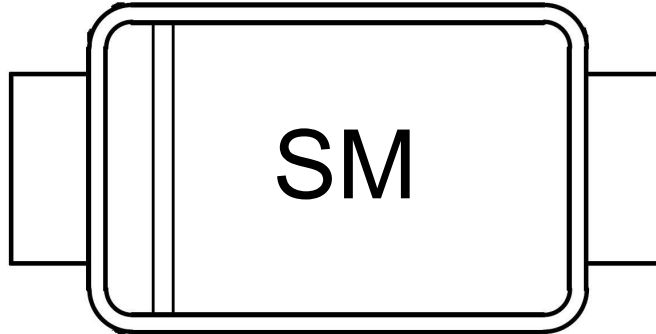


UNIT		A	C	D	E	e	H <sub>E</sub>	z
mm	max	1.0	0.25	1.8	1.35	0.4	2.7	8°
	min	0.8	0.05	1.6	1.15	0.25	2.3	
mil	max	39	9.8	71	53	18	106	
	min	31	2.0	63	45	10	91	

# Marking

Type number	Marking code
B16WSFL	SM

印章说明 / Marking Instructions



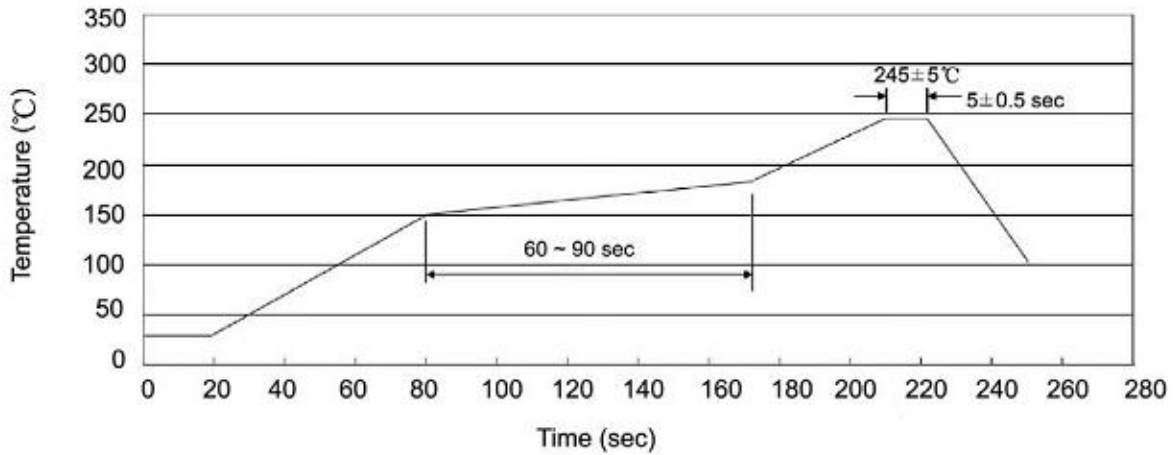
说明：

SM：为型号代码

Note:

SM：Product Type Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323FL	3000	8	24000	6	144000	7" ×8	185X180X105	390X385X205

**使用说明 / Notices**